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Abstract

In a stacked-chip semiconductor device, the circuit configuration of semiconductor chips can be used without requiring modification and without the need for mounting a
5 converter even if a plurality stacked semiconductor chips are electrically connected to each other.

Through-wires 5 disposed on semiconductor chip 4 receive a power supply voltage and ground from a thick-film wiring 2c by way of bumps 3. Therefore, a power supply
10 voltage and ground can be fed to desired locations of the upper semiconductor chip 4 by way of a short pathway, and the problem in which wiring resistance increases does not occur because rewiring is not required. For this reason, the operating stability of the semiconductor device is
15 increased.